Agilent 4 mm Super Oval Precision Optical Performance AllnGaP and InGaN LEDs

Data Sheet

SunPower Series Agilent HLMP-RG10, HLMP-SG10, HLMP-RL10, HLMP-SL10, HLMP-RD11, HLMP-SD11, HLMP-RL11, HLMP-SL11, HLMP-RM11, HLMP-SM11, HLMP-RB11, HLMP-SB11

Description

These Precision Optical Performance Oval LEDs are specifically designed for Full Color/Video and Passenger Information signs. The oval shaped radiation pattern $(60^{\circ} \times 120^{\circ})$ and high luminous intensity ensure that these devices are excellent for wide field of view outdoor applications where a wide viewing angle and readability in sunlight are essential. These lamps have very smooth, matched radiation patterns ensuring consistent color mixing in full color applications, message uniformity across the viewing angle of the sign.

High efficiency LED materials are used in these lamps: Aluminum Indium Gallium Phosphide (AlInGaP) for Red and Amber color and Indium Gallium Nitride (InGaN) for Blue and Green. There are two families of red and amber lamps, AlInGaP and the higher performance AlInGaP II. Each lamp is made with an advanced optical grade epoxy offering superior high temperature and high moisture resistance in outdoor applications. The package epoxy contains both uv-a and uv-b inhibitors to reduce the effects of long term exposure to direct sunlight.

Designers can select parallel (where the axis of the leads is parallel to the wide axis of the oval radiation pattern) or perpendicular orientation. Both lamps are available in tinted version.

Features

- Well defined spatial radiation
 pattern
- Viewing angle: major axis 120° minor axis 60°
- · High luminous output
- Two red and amber intensity levels AlInGaP (bright) and AlInGaP II (brightest)
- Colors
 626/630 nm red
 590/592 nm amber
 526 nm green
 470 nm blue
- · Superior resistance to moisture
- · UV resistant epoxy

Benefits

- Viewing angle designed for wide field of view applications
- Superior performance for outdoor environments
- Radiation pattern matched for red, green, and blue for full color sign

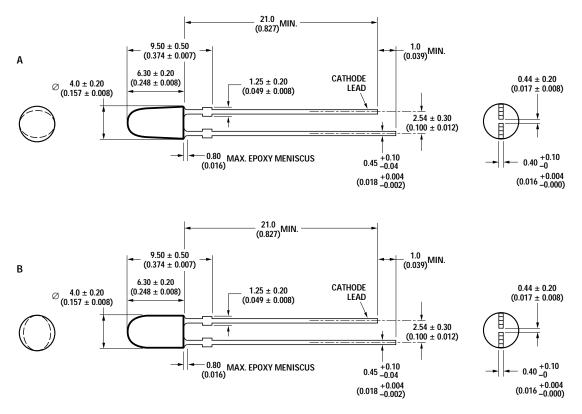
Applications

• Full color signs

CAUTION: The Blue and Green LEDs are Class 1 ESD sensitive. Please observe appropriate precautions during handling and processing. Refer to Agilent Technologies Application Note AN-1142 for additional details.



Package Dimensions



DIMENSIONS ARE IN MILLIMETERS (INCHES).

Device Selection Guide for AlInGaP

Part Number	Color and Dominant Wavelength λ _d (nm) Typ.	Lumino Intensit I _V (mcd Min.		Leads with Stand-Offs	Leadframe Orientation	Package Drawing
HLMP-SG10-JM000	Red 626	240	680	Yes	Perpendicular	А
HLMP-RG10-JM000	Red 626	240	680	Yes	Parallel	В
HLMP-SL10-LP0xx	Amber 590	400	1150	Yes	Perpendicular	А
HLMP-RL10-LP0xx	Amber 590	400	1150	Yes	Parallel	В

Notes:

1. The luminous intensity is measured on the mechanical axis of the lamp package.

2. The optical axis is closely aligned with the package mechanical axis.

3. The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the color of the lamp.

Part Number	Color and Dominant Wavelength A _d (nm) Typ.	Lumino Intensi I _V (mcd Min.		Leads with Stand-Offs	Leadframe Orientation	Package Drawing
HLMP-RD11-J0000	Red 630	240	-	Yes	Parallel	В
HLMP-RD11-LP000	Red 630	400	1150	Yes	Parallel	В
HLMP-RD11-LPT00	Red 630	400	1150	Yes	Parallel	В
HLMP-RL11-H0000	Amber 592	180	-	Yes	Parallel	В
HLMP-RL11-LP000	Amber 592	400	1150	Yes	Parallel	В
HLMP-RL11-LPRxx	Amber 592	400	1150	Yes	Parallel	В
HLMP-SD11-J0000	Red 630	240	-	Yes	Perpendicular	А
HLMP-SD11-LP000	Red 630	400	1150	Yes	Perpendicular	А
HLMP-SD11-LPT00	Red 630	400	1150	Yes	Perpendicular	А
HLMP-SD11-MN0xx	Red 630	520	880	Yes	Perpendicular	А
HLMP-SD11-MNTxx	Red 630	520	880	Yes	Perpendicular	А
HLMP-SL11-H0000	Amber 592	180	-	Yes	Perpendicular	А
HLMP-SL11-HL0xx	Amber 592	180	520	Yes	Perpendicular	А
HLMP-SL11-KN0xx	Amber 592	310	880	Yes	Perpendicular	А
HLMP-SL11-LP0xx	Amber 592	400	1150	Yes	Perpendicular	А
HLMP-SL11-LPRxx	Amber 592	400	1150	Yes	Perpendicular	А

Notes:

1. The luminous intensity is measured on the mechanical axis of the lamp package.

2. The optical axis is closely aligned with the package mechanical axis.

3. The dominant wavelength, λ_{d} , is derived from the CIE Chromaticity Diagram and represents the color of the lamp.

Device Selection Guide for InGaN

Dout Number	Color and Dominant Wavelength	- •	ty I) at 20 mA	Leads with	Leadframe	Package
Part Number	λ _d (nm) Typ.	Min.	Max.	Stand-Offs	Orientation	Drawing
HLMP-SM11-LP0xx	Green 526	400	1150	Yes	Perpendicular	A
HLMP-RM11-H00xx	Green 526	180	-	Yes	Parallel	В
HLMP-RM11-M00xx	Green 526	520	-	Yes	Parallel	В
HLMP-SB11-H00xx	Blue 470	180	-	Yes	Perpendicular	А
HLMP-RB11-D00xx	Blue 470	65	-	Yes	Parallel	В
HLMP-RB11-H00xx	Blue 470	180	-	Yes	Parallel	В

Notes:

4. The luminous intensity is measured on the mechanical axis of the lamp package.

5. The optical axis is closely aligned with the package mechanical axis.

6. The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the color of the lamp.

Part Numbering System HLMP - $\underline{x} \times \underline{xx}$ - $\underline{x} \times \underline{x} \times \underline{xx}$ **Mechanical Options** 00: Bulk Packaging DD: Ammo Pack YY: Flexi-Bin; Bulk Packaging ZZ: Flexi-Bin; Ammo Pack **Color Bin & V_F Selections** 0: No Color Bin Limitation R: Amber Color Bins 1, 2, 4, and 6 with V_F Maximum of 2.6 V T: Red Color with V_F Maximum of 2.6 V **Maximum Intensity Bin** 0: No Iv Bin Limitation **Minimum Intensity Bin Refer to Device Selection Guide** Color B: 470 nm Blue D: 630 nm Red G: 626 nm Red L: 590/592 nm Amber M: 526 nm Green Package R: 4 mm 60° x 120° Oval, Parallel S: 4 mm 60° x 120° Oval, Perpendicular

Absolute Maximum Ratings

 $T_A = 25^{\circ}C$

Blue and Green	Amber and Red	
30 mA	50 mA	
100 mA	100 mA	
30 mA	30 mA	
5 V	5 V	
120 mW	120 mW	
130°C	130°C	
-40°C to +80°C	-40°C to +100°C	
-40°C to +100°C	-40°C to +120°C	
	30 mA 100 mA 30 mA 5 V 120 mW 130°C -40°C to +80°C	30 mA 50 mA 100 mA 100 mA 30 mA 30 mA 5 V 5 V 120 mW 120 mW 130°C 130°C -40°C to +80°C -40°C to +100°C

Note:

1. Derate linearly as shown in Figures 6 and 7.

Electrical/Optical Characteristics

 $T_A = 25^{\circ}C$

Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Typical Viewing Angle ^[1]	20 _{1/2}				deg	
Major			120		-	
Minor			60			
Forward Voltage	V _F				V	I _F = 20 mA
Red ($\lambda_d = 626$ nm)			1.9	2.4		
Red ($\lambda_d = 630$ nm)			2.0	2.4 ^[2]		
Amber ($\lambda_d = 590$ nm)			2.02	2.4		
Amber ($\lambda_d = 592 \text{ nm}$)			2.15	2.4 ^[2]		
Blue ($\lambda_d = 470$ nm)			3.5	4.0		
Green ($\lambda_d = 526$ nm)			3.5	4.0		
Reverse Voltage	V _R				V	I _R = 100 μA
Amber and Red		5	20			
Blue and Green		5	-			
Peak Wavelength	λ_{PEAK}				nm	Peak of Wavelength of
Red ($\lambda_d = 626$ nm)	. באוג		635			Spectral Distribution
Red ($\lambda_d = 630$ nm)			639			at I _F = 20 mA
Amber ($\lambda_d = 590$ nm)			592			•
Amber ($\lambda_d = 592 \text{ nm}$)			594			

LED Indicators

Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Blue (λ _d = 470 nm)			467			
Green (λ_d = 526 nm)			524			
Spectral Halfwidth	$\Delta\lambda_{1/2}$				nm	Wavelength Width at
$\dot{R}ed (\lambda_d = 626/630 \text{ nm})$			17			Spectral Distribution
Amber ($\lambda_{d} = 590/592 \text{ nm}$)			17			$\frac{1}{2}$ Power Point at I _F = 20 mA
Blue ($\lambda_d = 470$ nm)			20			
Green (λ_d = 526 nm)			35			
Capacitance	С				рF	$V_{F} = 0, F = 1 MHz$
All Colors			40		·	
Thermal Resistance	$R\theta_{J-PIN}$				°C/W	LED Junction-to-Cathode
All Colors			240			Lead
Luminous Efficacy ^[3]	ην				lm/W	Emitted Luminous Power/
Red ($\lambda_d = 626 \text{ nm}$)			150			Emitted Radiant Power
Red ($\lambda_d = 630$ nm)			155			
Amber ($\lambda_d = 590$ nm)			480			
Amber ($\lambda_d = 592 \text{ nm}$)			500			
Blue ($\lambda_d = 470$ nm)			70			
Green ($\lambda_d = 526$ nm)			540			

Notes:

1. $2\theta_{1/2}$ is the off-axis angle where the luminous intensity is the on-axis intensity. 2. For options -xxRxx, -xxTxx, and -xxVxx, maximum forward voltage, V_F, is 2.6 V. Please refer to V_F Bin Table below. 3. The radiant intensity, I_e, in watts per steradian, may be found from the equation I_e = I_v/η_v, where I_v is the luminous intensity in candelas and η_v is the luminous efficacy in lumens/watt.

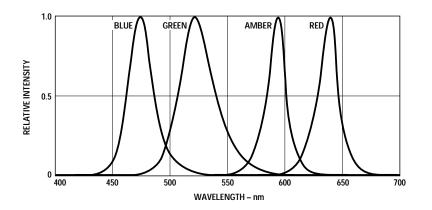


Figure 1. Relative intensity vs. wavelength.

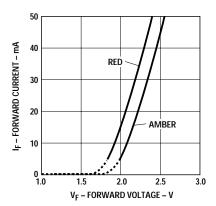
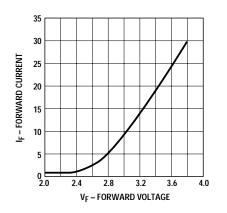


Figure 2. Amber, Red forward current vs. forward voltage.



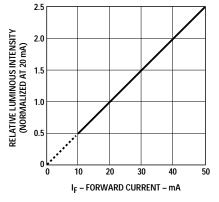
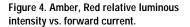


Figure 3. Blue, Green forward current vs. forward voltage.



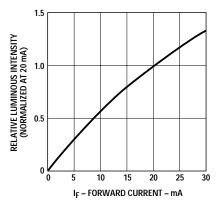
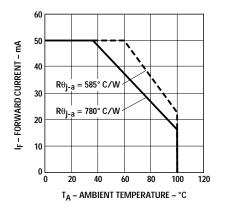


Figure 5. Blue, Green relative luminous intensity vs. forward current.



35 30 IF – FORWARD CURRENT – mA $R\theta_{j-a} = 585^{\circ} C/W$ 25 20 15 10 5 0 L 0 20 100 40 60 80 TA - AMBIENT TEMPERATURE - °C

Figure 6. Amber, Red maximum forward current vs. ambient temperature.

Figure 7. Blue, Green maximum forward current vs. ambient temperature.

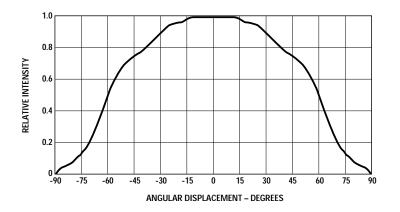


Figure 8a. Representative spatial radiation pattern for major axis.

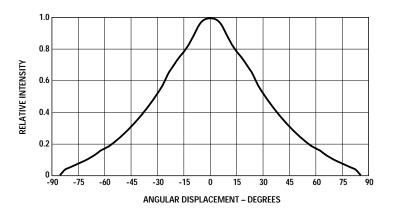


Figure 8b. Representative spatial radiation pattern for minor axis.

Color Bin Limits (nm at 20 mA)

	1					
Blue	Color Range (nm)					
Bin	Min.	Max.				
1	460.0	464.0				
2	464.0	468.0				
3	468.0	472.0				
4	472.0	476.0				
5	476.0	480.0				

Tolerance for each bin limit is $\pm \ 0.5 \ \text{nm}.$

Green	Color Range (nm)					
Bin ID	Min.	Max.				
1	520.0	524.0				
2	524.0	528.0				
3	528.0	532.0				
4	532.0	536.0				
5	536.0	540.0				

Tolerance for each bin limit is $\pm \ 0.5 \ \text{nm}.$

Intensity Bin Limits (mcd at 20 mA)

Bin Name	Min.	Max.
D	65	85
E	85	110
F	110	140
G	140	180
Н	180	240
J	240	310
К	310	400
L	400	520
М	520	680
N	680	880
Р	880	1150

Tolerance for each bin limit is \pm 15%.

VF Bin Table^[2]

Bin Name	Min.	Max.
VA	2.0	2.2
VB	2.2	2.4
VC	2.4	2.6

Tolerance for each bin is $\pm \ 0.05$ V.

Note:

1. Bin categories are established for classification of products. Products may not be available in all bin categories.

Amber	Color Range (nm)				
Bin ID	Min.	Max.			
1	584.5	587.0			
2	587.0	589.5			
4	589.5	592.0			
6	592.0	594.5			

Tolerance for each bin limit is ± 0.5 nm.

Note:

1. All bin categories are established for classification of products. Products may not be available in all bin categories. Please contact your Agilent representatives for further information.

Precautions

Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

Soldering Conditions

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

	Wave Soldering	Manual Solder Dipping
Pre-heat Temperature	105 °C Max.	-
Pre-heat Time	30 sec Max.	-
Peak Temperature	250 °C Max.	260 °C Max.
Dwell Time	3 sec Max.	5 sec Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25° C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

LED Component Lead Size	Diagonal	Plated Through Hole Diameter
0.457 x 0.457 mm	0.646 mm	0.976 to 1.078 mm
(0.018 x 0.018 inch)	(0.025 inch)	(0.038 to 0.042 inch)
0.508 x 0.508 mm	0.718 mm	1.049 to 1.150 mm
(0.020 x 0.020 inch)	(0.028 inch)	(0.041 to 0.045 inch)

Note: Refer to application note AN1027 for more information on soldering LED components.

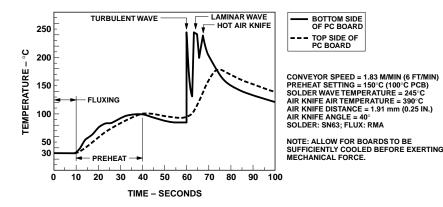


Figure 9. Recommended wave soldering profile.

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